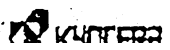


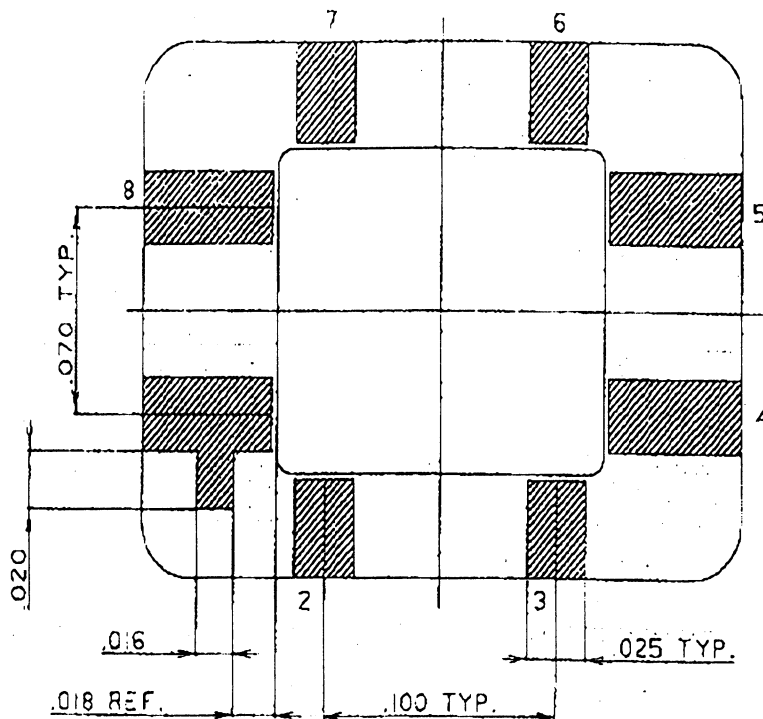
- NOTES
1. PLATING THICKNESS TO BE PER CUSTOMER'S SPECIFICATION.
 2. SEAL AREA TO BE METALLIZED.
 3. DIE ATTACH AREA TO BE METALLIZED.
 4. SEAL RING AND DIE ATTACH PADS TO BE FLOATING FROM ANY PINS.
 5. LEAD RESISTANCE : 0.200 MAX.

SB008U941-1 S=0
D=0

MODIFICATION	ADDED: .005 MIN. (.031 ± .010), .200 MAX. (.130 ± .020), .055 MAX. (.047 ± .008)	NAME	TOLERANCE	DRAWN	CHECKED	APPROVED	DATE	
	.235 ± .005 → .255 ± .005, .161 ± .005 → .181 ± .005	8 LEAD SIDE BRAZED PACKAGE	UNLESS OTHERWISE SPECIFIED	S.F	K.K	M.K	DEC.13.88	
	CHANGED: .400 ± .008 → .394 ± .008, JAN.20.89 S.F K.K M.K	SCALE 8/1	MATERIAL AS INDICATED	.005				
				THRU HOLE PLATING				
				DRAWING NO.			SHEET	



KYOCERA CORPORATION



BONDING PATTERN

MODIFICATION										
					NAME	TOLERANCE	DRAWN	CHECKED	APPROVED	DATE
					8 LEAD SIDE BRAZED PACKAGE	UNLESS OTHERWISE SPECIFIED	S.F	K.K	M.K	DEC.13'88
					SCALE 20/1	MATERIAL				
						THIRD ANGLE PROJECTION	<i>S. F. [Signature]</i>	<i>K. K. [Signature]</i>	<i>M. K. [Signature]</i>	
						HYDRODA CORPORATION	DRAWING NO.			1 OF 1